

AMENDMENTS TO THE CLAIMS:

This listing of claims replaces all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) An electrical component comprising:
~~with~~ a substrate (SU) comprising the one or more terminal contacts (ANK) for one or more electrical component structures (BS) on a ~~main~~ surface of the substrate,
~~with~~ a cover (AD) having a first surface and a second surface, the cover comprising:
the one or more terminal pads (AF) on the first surface;
one or more outside contacts on the second surface; and
electrical throughplatings electrically connecting the terminal pads on the first
surface and the outside contacts on the second surface; wherein (D) ~~with said~~
connected outside contacts (AUK), in which the cover is located on the main surface
of the substrate; and
a conductive adhesive in one or more cavities between the substrate and the cover, the
conductive adhesive forming an in which the electrical connection is made between the terminal
contacts on the substrate and the terminal pads, on the undersurface of the cover via cavities
~~(KV) completely filled with conductive adhesive (LK), which are arranged between the substrate~~
~~and cover.~~

2. (Currently Amended) The electrical [[A]] component as defined in of claim 1, wherein
~~in which the cavities (KV) are cut from~~ extend from an ~~one~~ outer edge of the component, ~~(BE) or~~
~~at least are provided in the direct vicinity of an outer edge.~~

3. (Currently Amended) The electrical [[A]] component as defined in of claim 1, further
comprising or 2, an interface layer in which between the substrate (SU) and the cover, wherein
~~(AD) an interface layer is provided in which~~ the cavities (KV) are ~~formed~~ in the interface layer.

4. (Currently Amended) The [[A]] component as defined in one of the Claims 1 to 3
claim 1, further comprising in which an enclosed frame structure (RS) is ~~provided~~
between the substrate (SU) and the cover (AD) in ~~the~~ an area of ~~the~~ an outer edge of the electrical component,
the enclosed frame structure comprising which comprises limited one or more recesses which
~~point towards the inside, above and below from the substrate and cover, which~~ that form the
~~show the aforesaid cavities, (KV).~~

5. (Currently Amended) The [[A]] component as defined in of claim 4, wherein:
[[-]] in which the enclosed frame structure (RS) encloses the electrical component
structures ~~(BS),~~
[[-]] in which the terminal contacts on the substrate (ANK) are provided outside the
frame structure, and

~~[[-]] in which~~ the substrate is in direct contact with a first side of the enclosed frame structure (SU) and the cover (AD) each are seated flat on one is in direct contact with a second side of the framed enclosed frame structure, so that an enclosed cavity (HR) is formed which accommodates the component structures.

6. (Currently Amended) The ~~[[A]] component as defined in one of the Claims 1 to 5, of claim 1, wherein~~ in that the cover (AD) includes a plurality of at least is a dielectric layer layers and a plurality of metallizations (DS) comprising the carrier, in which circuit elements comprising the structured metallizations (ML) are provided on a dielectric layer or between among the dielectric layers respectively.

7. (Currently Amended) The ~~[[A]] component as defined in one of the Claims 1 to 6, in which of claim 1, wherein~~ the conductive adhesive comprises (LK) is a reaction resin configured to harden which hardens at low temperatures, the reaction resin including and is filled with electrically conducting particles.

8. (Currently Amended) A process for producing a component, the component including ~~[[-]] in which on~~ a substrate (SU) that includes several component regions that are provided for a component (BE), which respectively comprise component structures (BS) and terminal contacts (ANK), in which the substrate and a cover having a surface, the cover including (AD), which on

~~one side comprises electrical terminal pads on the surface; the method for producing the~~
component comprising:

arranging the cover such that (AF) corresponding to the terminal contacts, are so fitted
~~above each other that~~ at least some of the terminal pads and contacts are located substantially
opposite corresponding ones of the terminal contacts one another in cavities, wherein (KV), [[]]
~~in which the cavities of several~~ a plurality of the component regions are connected via channels;
(CH);

[[-]] forming an electrical contact between terminal contacts and corresponding terminal
pads by injecting in which a conductive adhesive (LK) is injected into the channels until all the
cavities are substantially filled with the conductive adhesive; and , in which an electric contact is
~~created between the terminal contacts and the corresponding electrical terminal pads;~~

[[-]] separating the in which per component regions such that region a component is
separated, in which the electrical connection connections between the cavities is separated are
interrupted.

9. (Currently Amended) The process as defined in of claim 8, further comprising:

arranging [[-]] in which a frame structures structure (RS) is provided between the
substrate (SU) and the cover such that a particular frame structure (AD) per component region,
~~which encloses the~~ a particular component region and , in which only the terminal contacts for
the particular component region are located (ANK) are provided outside the particular enclosed
frame structure, wherein (RS), in which the channels (CH) are created formed between the frame

structures of adjacent component regions and the channels are ~~enclosed above and below~~
covered by the substrate and the cover.

10. (Currently Amended) The ~~[[A]]~~ process ~~as defined in~~ of claim 8, wherein the
conductive adhesive comprises ~~or 9, in which~~ a reaction resin that includes ~~filled with~~ electrically
conducting particles ~~is used as conductive adhesive (LK).~~

11. (Currently Amended) The ~~[[A]]~~ process ~~as defined in one of the Claims 9 or 10 of~~
claim 9, further comprising:

producing in which the frame structures (RS) ~~is produced by structuring a photoresist,~~
~~which in advance is applied in large areas~~ applying a photoresist onto one or both of the ~~opposite~~
~~surfaces of the substrate (SU) and the cover; and (AD).~~

patterning the photoresist.

12. (Currently Amended) The ~~[[A]]~~ process ~~as defined in one of the Claims 9 to 11, of~~
claim 9, further comprising:

producing in which the frame structures ~~structure (RS) is produced~~ on a surface of the a
substrate; ~~(SU) or the cover (AD), and~~

bonding the frame structures to ~~is bonded with the cover, or the substrate, or in which on~~
~~both surfaces corresponding frame structures (RS) are produced and glued together.~~

13. (Currently Amended) The [[A]] process as defined in one of the Claims 9 to 12, of claim 9, further comprising planarising in which the frame structures, (RS) are planarized prior to being placed above each other, so that the upper edges of all frame structures is located on the same level.

14. (Currently Amended) The [[A]] process as defined in one of the Claims 8 to 13, of claim 8, wherein injecting the conductive adhesive comprises injecting the in which the conductive adhesive (LK) is injected under pressure into the channels, (CH).

15. (Currently Amended) The [[A]] process as defined in one of the Claims 8 to 14, of claim 8, wherein separating the component regions further comprises:

sawing the component to separate the component regions, wherein sawing comprises:

forming saw cuts in a direction substantially in which the separation is performed by means of sawing, in which the saw cuts are performed parallel to the channels (CH), in which the cavities (KV) of each channel are so cut such that the conductive adhesive (LK) exclusively remains in the cut cavities and such that, but in the channels said cavities are separated from cavities. or removed during the sawing process.

16. (Currently Amended) The [[A]] process as defined in one of the Claims 8 to 15, in which of claim 15, further comprising sealing at least the cutting one or more edges of the frame structure (RS) are sealed with a coating.

17. (Currently Amended) The [[A]] process of as defined in claim 16, in which after the separation the coating is produced by means of the wherein sealing one or more edges of the frame structure comprises sealing one or more edges of the frame structure using a method selected from the group consisting of applying a varnish application of varnish or and using chemical vapor disposition deposition.

18. (Currently Amended) The [[A]] process as defined in one of the Claims 8 to 17, in which of claim 8, wherein:

the cavities (KV) per component region are provided only at one longitudinal edge of the component regions; and

in which the channels (CH) are substantially provided parallel to this the one longitudinal edge and are arranged essentially run in a substantially straight line, within the configuration consisting of substrate (SU) and cover (AD).

19. (Currently Amended) The [[A]] process as defined in one of the Claims 8 to 18, of claim 15, wherein sawing to separate the component regions further comprises:

~~in which making~~ a first saw cut with a first relatively large cutting width to electrically separate (SB1) ~~is performed from the substrate (SU) or the cover (AD) parallel to the channel (CH), that the cavities (KV) filled with the conductive adhesive (LK) are separated electrically from one another and to form a the channel is opened at the top,~~

filling the ~~in which the opened~~ channel is filled with insulating material; and (IM),

making ~~in which subsequently a second continuous saw cut is made with relatively low a second cutting width (SB2), in which the saw cut is made at a distance to the opened cavities in the first saw cut, the second cutting width being less than the first cutting width.~~

20. (Currently Amended) The [[A]] process as defined in claim 19, wherein filling the channel with insulating material comprises filling less than all of the channel in which the open channel is not completely filled with [[an]] a single layer of the insulating material. (IM), and in which only one layer of an insulating material (IM) is deposited or applied.

21. (Currently Amended) The [[A]] process as defined in one of the Claims 8 to 20, in which of claim 15 wherein the cover comprises a printed circuit board comprised made of synthetic material is used as cover (AD), and the method further comprises applying in which prior to the separation a thermal mechanically adjusted synthetic layer is so applied to the a back side of the substrate. (SU) that a symmetric layered structure is obtained in terms of the thermal expansion characteristics.

22. (New) The electrical component of claim 1, wherein the cavities are arranged in a vicinity of an outer edge of the electrical component.

23. (New) The process of claim 9, further comprising:
producing the frame structure on a surface of the cover; and
bonding the frame structure to the substrate.

24. (New) The process of claim 9, further comprising:
producing a first portion of the frame structure on a surface of the a substrate;
producing a second portion of the frame structure on a surface of the cover; and
bonding the first portion of the frame structure to the second portion of the frame structure.